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(54) POWER SEMICONDUCTOR DEVICE

(71) Applicant: Mitsubishi Electric Corporation,

Tokyo (JP)

Inventors: Yukimasa HIGASHI, Tokyo (JP); Koji

YAMAMOTO, Tokyo (JP)

Assignee: Mitsubishi Electric Corporation,

Tokyo (JP)

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(57)ABSTRACT

The object of the present disclosure is to provide a power semiconductor device capable of miniaturization. According to the present disclosure power semiconductor device includes a semiconductor switching element configured to control a current flowing through a primary coil composing an ignition coil, and a control circuit configured to control drive of the semiconductor switching element, in which the control circuit includes a first constant current source, a first transistor with an output terminal thereof connected to a control terminal of the semiconductor switching element, a resistor with one end thereof connected to a control terminal of the first transistor and an other end thereof connected to the constant current source, a capacitor with one end thereof connected to the control terminal of the first transistor and an other end thereof grounded, and a second transistor with an input terminal thereof connected to the resistor and an output terminal grounded.

